

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---|----------|------------------|---------|------------------|
| L1 | 3 | (substrate and flip chip and gold-tin OR Au-Sn AND bonding AND sealed AND alloy).CLM. | US-PGPUB | AND | OFF | 2006/04/13 12:03 |

